

Notice Concerning Separation of Tera Probe's Wafer Level Packages (WLP) Business and Transfer of WLP Shares

Yokohama, Japan, September 1, 2015

Tera Probe announced that the company's board of directors today approved a basic agreement with AOI electronics Co., Ltd. that will split off Tera Probe's wafer level packages business into a new separate company and that will transfer all shares of the new company to AOI ELECTRONICS. Details appear below.

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1. Reason for the decision to transfer the WLP business

Wafer level packages (WLP) are used in smartphones and other small, low-power consumption electronic devices that require high-density engineering. WLP have high growth potential due to expected future use in Internet of Things (IoT) equipment and other products.

AOI ELECTRONICS has special technology related to packages and operates an electronic components business that centers on integrated circuit production. Also, the company is an important partner of Tera Probe. In order to expand WLP business possibilities while helping customers to meet their needs for this technology, Tera Probe has decided that transferring its WLP business to AOI ELECTRONICS creates substantial benefits.

In making this business decision Tera Probe will maintain its focus on its testing business. Also, AOI ELECTRONICS and Tera Probe will continue as partners and jointly leverage their respective strengths to meet a variety of customer needs.

The transfer of shares will only affect the new company's capital structure. The WLP processing services (manufacturing line, materials, equipment, processing, etc.) provided by the existing Ome Operation Center will not change.

2. Transfer schedule

(1)	Basic agreement approved	September 1, 2015
(2)	Supplementary agreement (tentative)	Late October 2015
(3)	Date of separation into new company (tentative)	April 1, 2016
(4)	Date of transfer of all shares (tentative)	April 1, 2016

NEWS RELEASE

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